SN74ACT564 Octal D-Type Edge-Triggered Flip-Flops with 3-State Outputs

1 Features

- Operation of 4.5V to 5.5V V_{CC}
- Inputs accept voltages to 5.5V
- Max t_{pd} of 8.5ns at 5V
- Inputs are TTL-voltage compatible
- 3-state inverted outputs drive bus lines directly
- Flow-through architecture to optimize PCB layout
- Full parallel access for loading

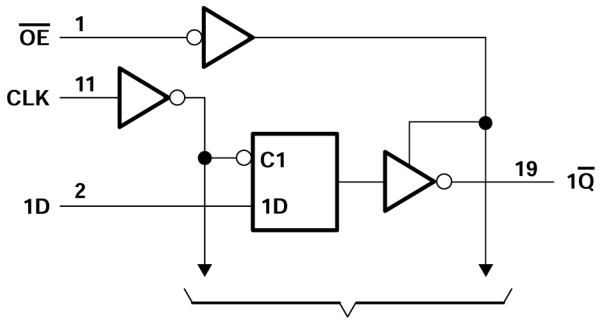
2 Description

The ’ACT564 devices are octal D-type edge-triggered flip-flops that feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

Package Information

PART NUMBER	PACKAGE(1)	PACKAGE SIZE(2)	BODY SIZE(3)
SN74ACT564	DW (SOIC, 20)	12.8mm × 10.3mm	12.8mm × 7.5mm
	N (PDIP, 20)	24.33mm × 9.4mm	24.33mm × 6.35mm
	NS (SOP, 20)	12.6mm × 7.8mm	12.6mm × 5.3mm
	PW (TSSOP, 20)	6.5mm × 6.4mm	6.5mm × 4.4mm

(1) For more information, see Section 10.
(2) The package size (length × width) is a nominal value and includes pins, where applicable.
(3) The body size (length × width) is a nominal value and does not include pins.



Logic Diagram (Positive Logic)

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3 Pin Configuration and Functions

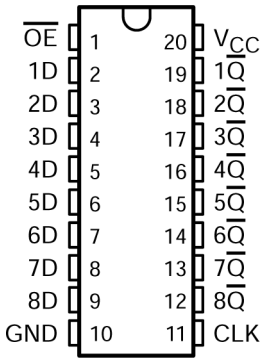


Figure 3-1. SN74ACT564 DB, DW, N, NS, or PW Package (Top View)

Table 3-1. Pin Functions

PIN		TYPE	Description
NO.	NAME		
1	$\overline{OE}$	I	Clear all channels, active low
2	1D	I	Channel 1, D input
3	2D	I	Channel 2, D input
4	3D	I	Channel 3, D input
5	4D	I	Channel 4, D input
6	5D	I	Channel 5, D input
7	6D	I	Channel 6, D input
8	7D	I	Channel 7, D input
9	8D	I	Channel 8, D input
10	GND	—	Ground
11	CLK	I	Clock Pin
12	8Q	O	Channel 8, Q output
13	7Q	O	Channel 7, Q output
14	6Q	O	Channel 6, Q output
15	5Q	O	Channel 5, Q output
16	4Q	O	Channel 4, Q output
17	3Q	O	Channel 3, Q output
18	2Q	O	Channel 2, Q output
19	1Q	O	Channel 1, Q output
20	V_{CC}	—	Power Pin

4 Specifications

4.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		–0.5	7	V
V_I (2)	Input voltage range		–0.5	V_{CC} + 0.5	V
V_O (2)	Output voltage range		–0.5	V_{CC} + 0.5	V
I_{IK}	Input clamp current	(V_I < 0 or V_I > V_{CC})		±20	mA
I_{OK}	Output clamp current	(V_O < 0 or V_O > V_{CC})		±20	mA
I_O	Continuous output current	(V_O = 0 to V_{CC})		±50	mA
	Continuous current through V_{CC} or GND			±200	mA
T_{stg}	Storage temperature range		–65	150	°C

(1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

4.2 Recommended Operating Conditions

(over operating free-air temperature range (unless otherwise noted)(1)

		SN74ACT564		UNIT
		MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	V
V_{IH}	High-level input voltage	2		V
V_{IL}	Low-level input voltage		0.8	V
V_I	Input voltage	0	V_{CC}	V
V_O	Output voltage	0	V_{CC}	V
I_{OH}	High-level output current		–24	mA
I_{OL}	Low-level output current		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		8	ns/V
T_A	Operating free-air temperature	–40	85	°C

(1) All unused inputs of the device must be held at V_{CC} or GND for proper device operation. Refer to the TI application report *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

4.3 Thermal Information

THERMAL METRIC(1)		SN74ACT564					UNIT
		DB (SSOP)	DW (SOIC)	N (PDIP)	NS (SO)	PW (TSSOP)	
		20 PINS	20 PINS	20 PINS	20 PINS	20 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	70	101.2	69	106.2	126.2	°C/W

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report (SPRA953).

4.4 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN74ACT564		UNIT
			MIN	TYP	MAX	MIN	MAX	
V_{OH}	I_{OH} = –50 µA	4.5 V	4.4	4.49		4.4		V
		5.5 V	5.4	5.49		5.4		
	I_{OH} = –24 mA	4.5 V	3.86			3.76		
		5.5 V	4.86			4.76		
	I_{OH} = –50 mA(1)	5.5 V						
	I_{OH} = –75 mA(1)	5.5 V				3.85		
V_{OL}	I_{OL} = 50µA	4.5 V			0.1		0.1	V
		5.5 V			0.1		0.1	
	I_{OL}= 24 mA	4.5 V			0.36		0.44	
		5.5 V			0.36		0.44	
	I_{OL} = 50 mA(1)	5.5 V						
	I_{OL} = 75 mA(1)	5.5 V					1.65	
I_{OZ}	V_O = V_{CC} or GND	5.5 V			±0.25		±2.5	µA
I_I	V_I = V_{CC} or GND	5.5 V			±0.1		±1	µA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			4		40	µA
ΔI_{CC} (2)	One input at 3.4 V, Other inputs at GND or V_{CC}	5.5 V		0.6			1.5	mA
C_i	V_I = V_{CC} or GND	5 V		4.5				pF
C_o	V_O = V_{CC} or GND	5 V		15				pF

(1) Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.
(2) This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V_{CC}.

4.5 Timing Requirements

over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Load Circuit and Voltage Waveforms)

		T_A = 25°C		SN74ACT564		UNIT
		MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency		85		75	MHz
t_w	Pulse duration, CLK high or low	3		3.5		ns
t_{su}	Setup time, data before CLK↑	2.5		3		ns
t_h	Hold time, data after CLK↑	1		1		ns

4.6 Switching Characteristics

over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Load Circuit and Voltage Waveforms)

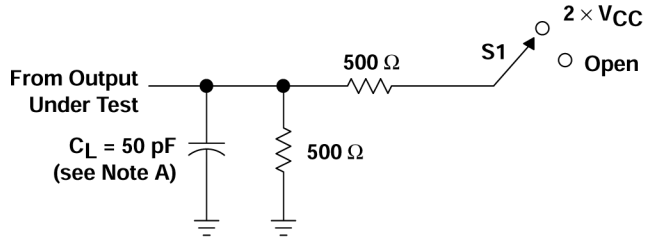
PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN74ACT564		UNIT
			MIN	TYP	MAX	MIN	MAX	
f_{max}			85	90		75		MHz
t_{PLH}	CLK	$\overline{Q}$	2	6.5	10.5	1.5	11.5	ns
t_{PHL}			1.5	6	9.5	1.5	10.5	
t_{PZH}	$\overline{OE}$	$\overline{Q}$	1.5	5.5	9	1.5	9.5	ns
t_{PZL}			1.5	5.5	8.5	1	9.5	
t_{PHZ}	$\overline{OE}$	$\overline{Q}$	1.5	7	10.5	1.5	11.5	ns
t_{PLZ}			1.5	5	8	1	8.5	

4.7 Operating Characteristics

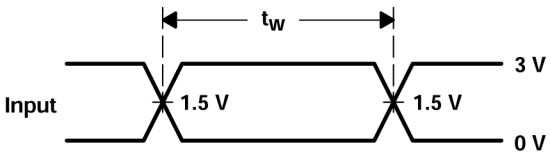
V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS		TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF,	f = 1 MHz	50	pF

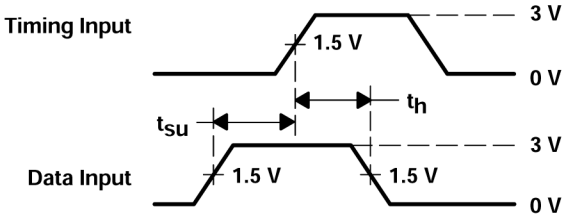
5 Parameter Measurement Information



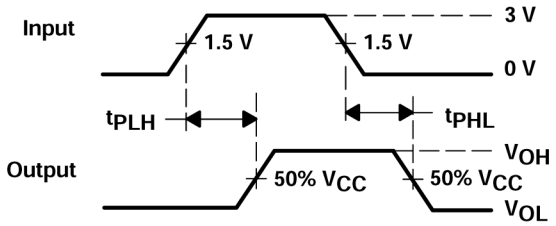
LOAD CIRCUIT



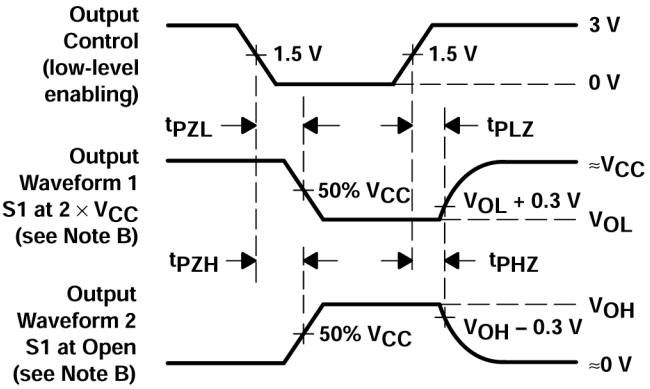
VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, ZO = 50 Ω, tr ≤ 2.5 ns, tf ≤ 2.5 ns.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 5-1. Load Circuit and Voltage Waveforms

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 × V_{CC}
t_{PHZ}/t_{PZH}	Open

6 Detailed Description

6.1 Overview

On the positive transition of the clock (CLK) input, the $\overline{Q}$ outputs are set to the complements of the logic levels set up at the data (D) inputs.

A buffered output-enable ($\overline{OE}$) input places the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

$\overline{OE}$ does not affect internal operations of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

For specified high-impedance state during power up or power down, $\overline{OE}$ must be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

6.2 Functional Block Diagram

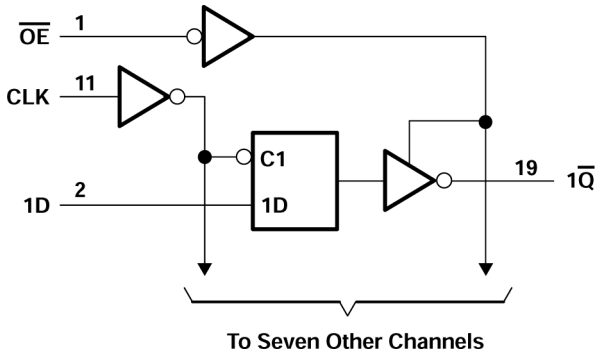


Figure 6-1. Logic Diagram (Positive Logic)

6.3 Device Functional Modes

Table 6-1. Function Table (Each Flip-flop)

INPUTS			OUTPUT $\overline{Q}$
$\overline{OE}$	CLK	D	
L	↑	H	L
L	↑	L	H
L	H or L	X	$\overline{Q}_0$
H	X	X	Z

7 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

7.1 Power Supply Recommendations

The power supply can be any voltage between the min and max supply voltage rating located in *Section 4.2*.

Each V_{CC} terminal should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, TI recommends 0.1 µF and if there are multiple V_{CC} terminals, then TI recommends .01 µF or .022 µF for each power terminal. It is okay to parallel multiple bypass capacitors to reject different frequencies of noise. A 0.1 µF and 1 µF are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results.

7.2 Layout

7.2.1 Layout Guidelines

When using multiple bit logic devices inputs should not ever float.

In many cases, functions or parts of functions of digital logic devices are unused, for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. Specified below are the rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or V_{CC} whichever make more sense or is more convenient. It is generally okay to float outputs unless the part is a transceiver. If the transceiver has an output enable pin it will disable the outputs section of the part when asserted. This does not disable the input section of the IOs so they cannot float when disabled.

7.2.2 Layout Example

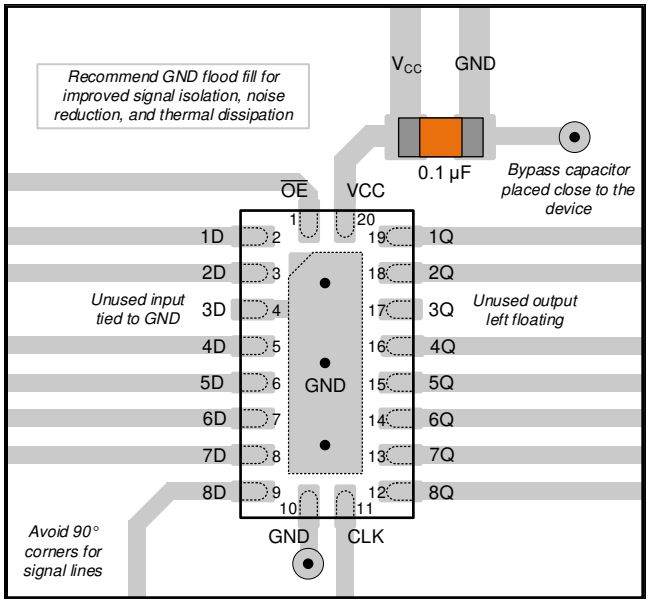


Figure 7-1. Example layout for the SN74ACT564

8 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

8.1 Documentation Support (Analog)

8.1.1 Related Documentation

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 8-1. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
SN74ACT564	Click here	Click here	Click here	Click here	Click here

8.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

8.3 Support Resources

TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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8.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.
All trademarks are the property of their respective owners.

8.5 Electrostatic Discharge Caution

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

8.6 Glossary

TI Glossary — This glossary lists and explains terms, acronyms, and definitions.

9 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision C (August 2023) to Revision D (February 2024)	Page
• Added body size to *Package Information* table	1
• Updated RθJA values: DW = 58 to 101.2, NS = 60 to 106.2, PW = 83 to 126.2, all values in °C/W	4

Changes from Revision B (November 2002) to Revision C (August 2023)	Page
• Added *Package Information* table, *Pin Functions* table, *Thermal Information* table, *Device Functional Modes, Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section	1
• Removed references to SN54ACT564	1

10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74ACT564DW	Obsolete	Production	SOIC (DW) | 20	-	-	Call TI	Call TI	-40 to 85	ACT564
SN74ACT564DWR	Active	Production	SOIC (DW) | 20	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT564
SN74ACT564DWR.A	Active	Production	SOIC (DW) | 20	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT564
SN74ACT564N	Active	Production	PDIP (N) | 20	20 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74ACT564N
SN74ACT564N.A	Active	Production	PDIP (N) | 20	20 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74ACT564N
SN74ACT564NSR	Active	Production	SOP (NS) | 20	2000 | LARGE T&R	Yes	NIPDAU | NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT564
SN74ACT564NSR.A	Active	Production	SOP (NS) | 20	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT564
SN74ACT564PW	Obsolete	Production	TSSOP (PW) | 20	-	-	Call TI	Call TI	-40 to 85	AD564
SN74ACT564PWR	Active	Production	TSSOP (PW) | 20	2000 | LARGE T&R	Yes	NIPDAU | NIPDAU	Level-1-260C-UNLIM	-40 to 85	AD564
SN74ACT564PWR.A	Active	Production	TSSOP (PW) | 20	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AD564

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

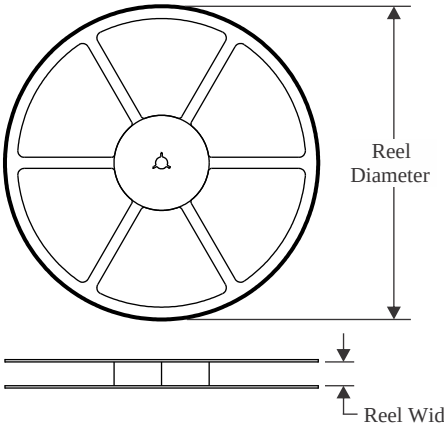
Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative

and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

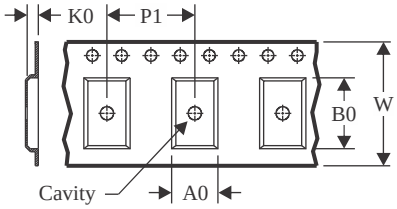
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

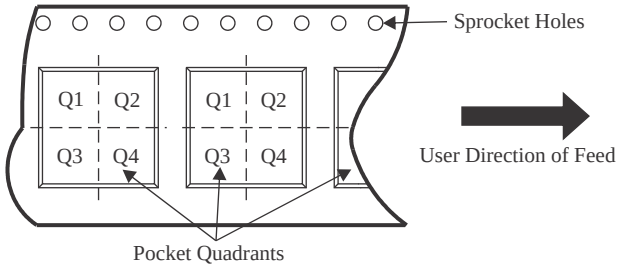


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

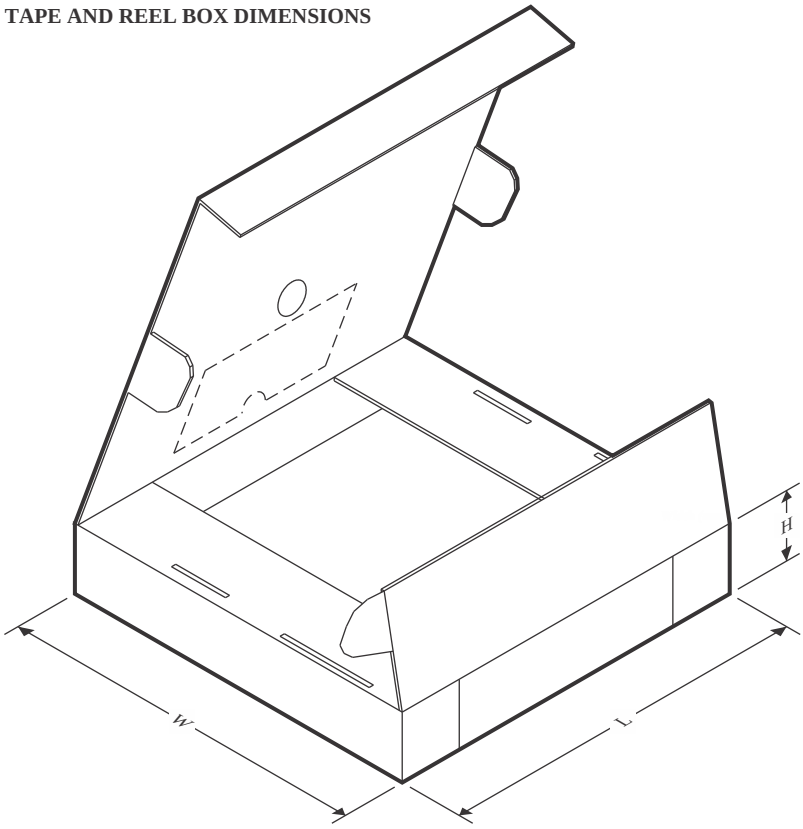
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ACT564DWR	SOIC	DW	20	2000	330.0	24.4	10.9	13.3	2.7	12.0	24.0	Q1
SN74ACT564DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74ACT564NSR	SOP	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74ACT564NSR	SOP	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74ACT564PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1
SN74ACT564PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

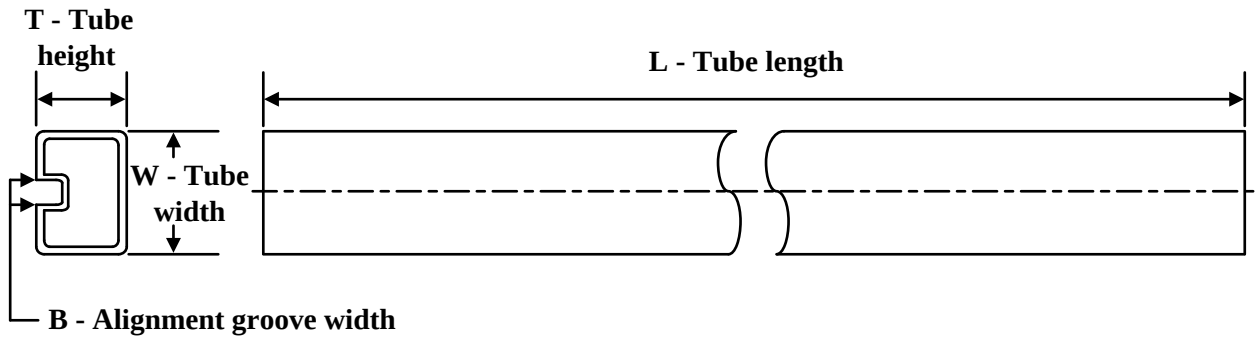
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ACT564DWR	SOIC	DW	20	2000	356.0	356.0	45.0
SN74ACT564DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ACT564NSR	SOP	NS	20	2000	356.0	356.0	45.0
SN74ACT564NSR	SOP	NS	20	2000	367.0	367.0	45.0
SN74ACT564PWR	TSSOP	PW	20	2000	353.0	353.0	32.0
SN74ACT564PWR	TSSOP	PW	20	2000	356.0	356.0	35.0

TUBE



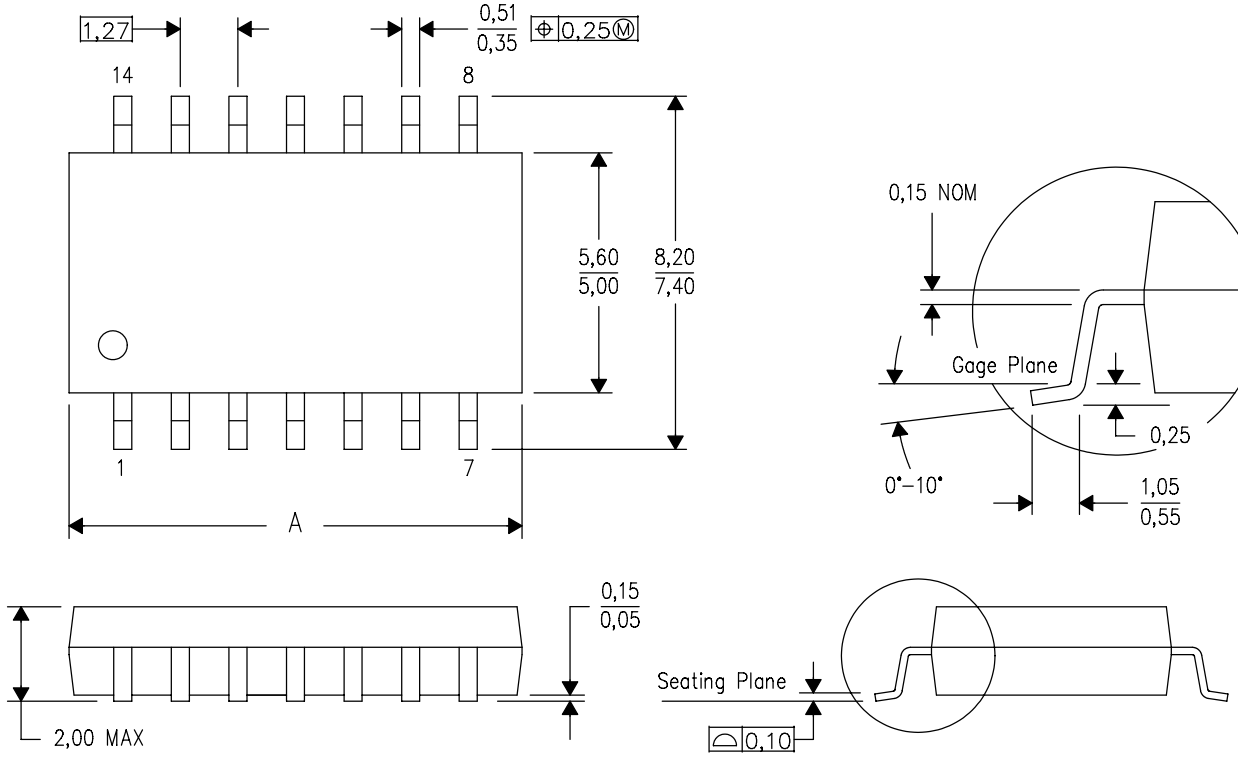
*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74ACT564N	N	PDIP	20	20	506	13.97	11230	4.32
SN74ACT564N.A	N	PDIP	20	20	506	13.97	11230	4.32

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

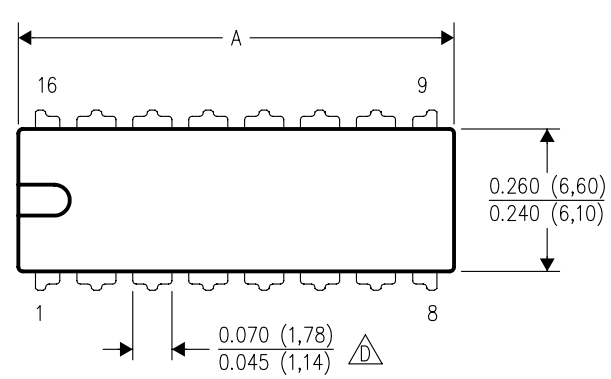
4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

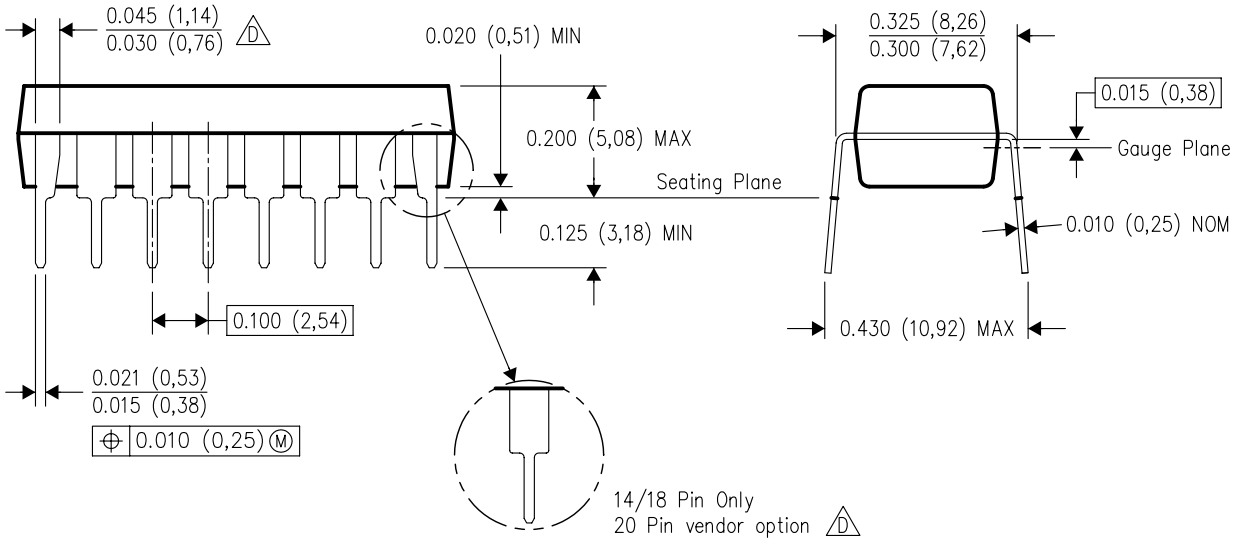
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN

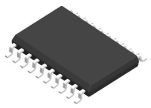


DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

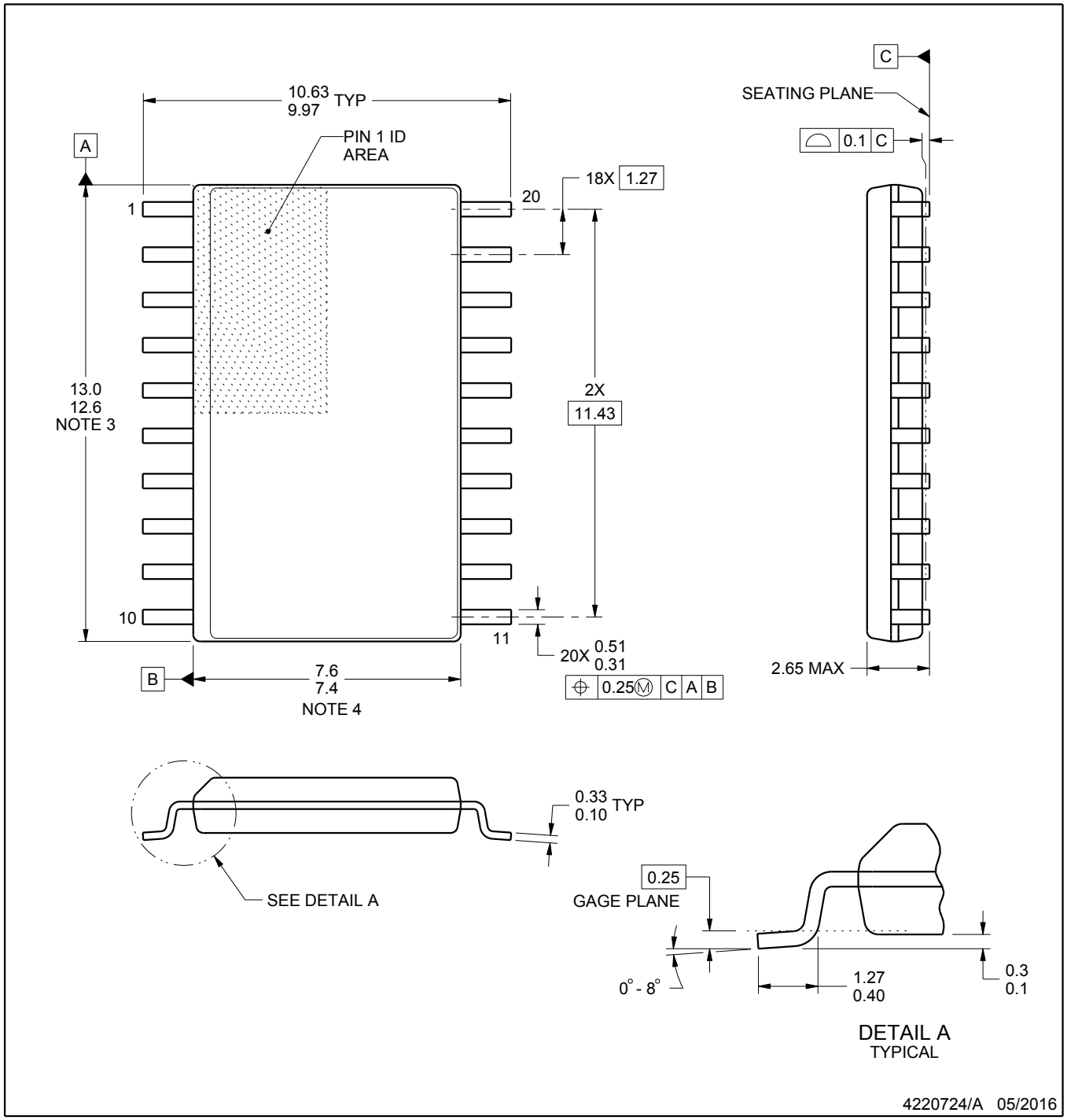


PACKAGE OUTLINE

DW0020A

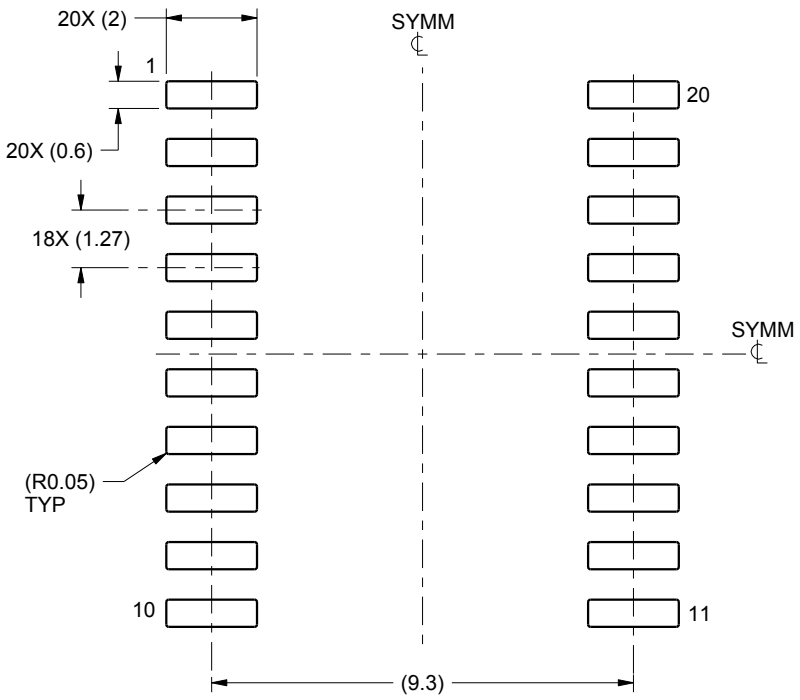
SOIC - 2.65 mm max height

SOIC

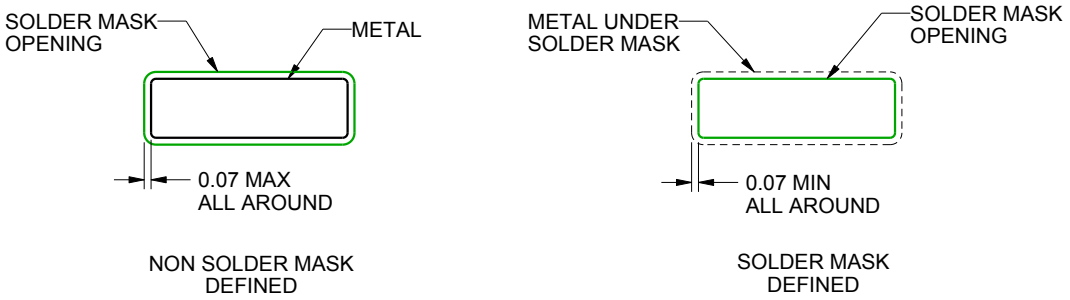


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.



LAND PATTERN EXAMPLE
SCALE:6X

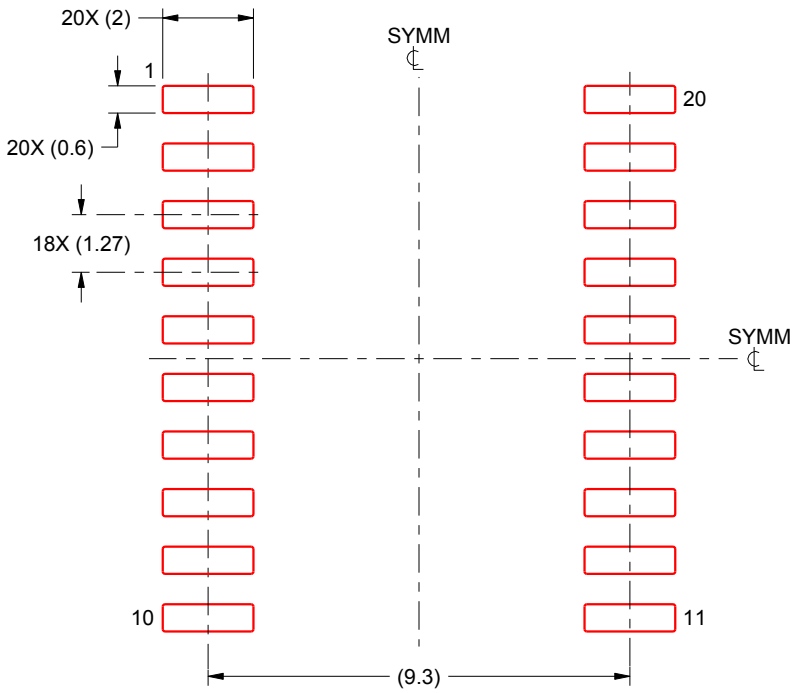


SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

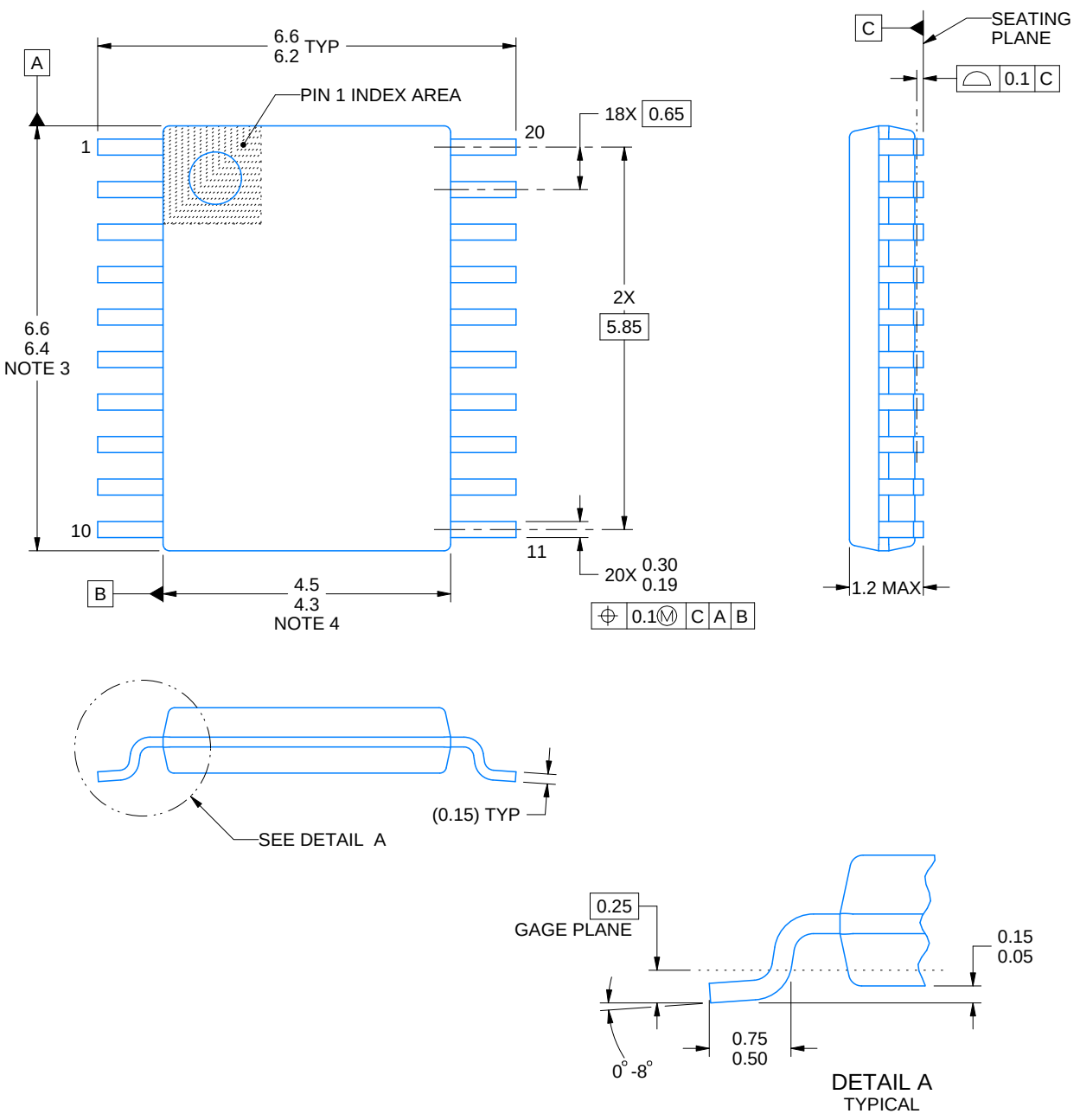
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PACKAGE OUTLINE

PW0020A

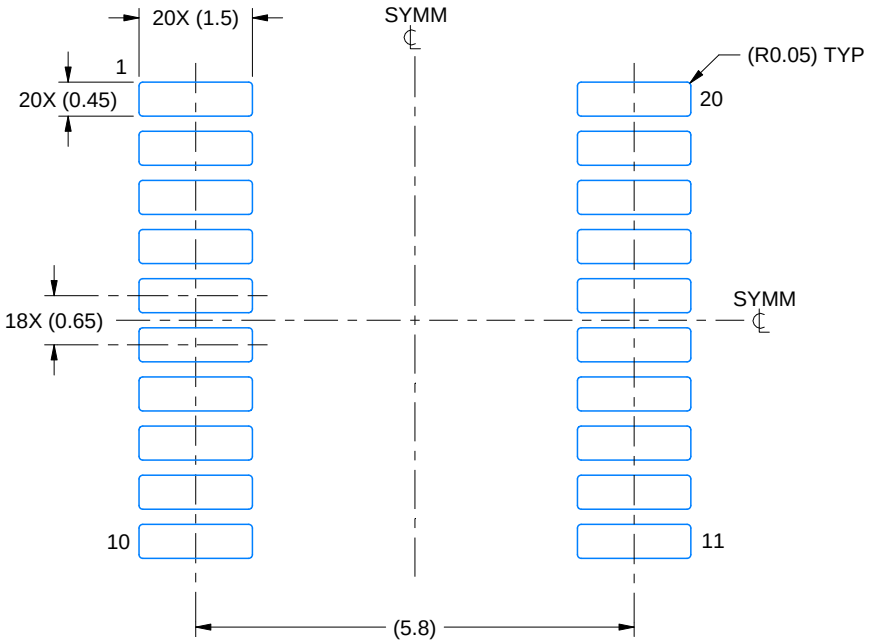
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



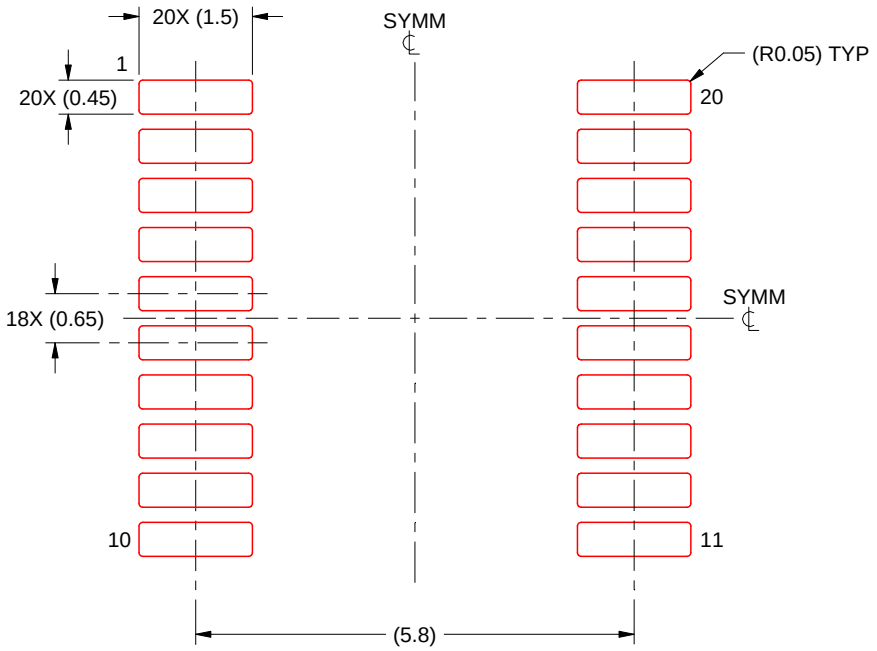
LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

SOLDER MASK DETAILS

4220206/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220206/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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